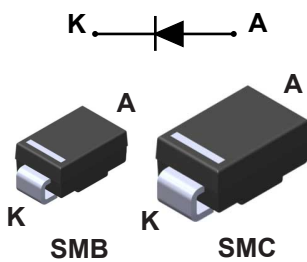


## 600 V - 3 A high efficiency ultrafast diode


**DO-201AD**

### Features

- Ultrafast switching
- Low forward voltage drop
- Low thermal resistance
- Low leakage current (platinum doping)
- Planar technology
- ECOPACK compliant

### Applications

- Switching diode
- Auxiliary power supply

### Description

The STTH3R06, which uses ST ultrafast high voltage planar technology, is specially suited for free-wheeling, clamping, snubbing, demagnetization in power supplies and other power switching applications.

Product status	
STTH3R06	
Product summary	
Symbol	Value
$I_{F(AV)}$	3 A
$V_{RRM}$	600 V
$T_{j(max.)}$	175 °C
$V_{F(typ.)}$	1.00 V
$t_{rr(max.)}$	35 ns

# 1 Characteristics

**Table 1. Absolute ratings (limiting values at 25 °C, unless otherwise specified)**

Symbol	Parameter		Value	Unit	
$V_{RRM}$	Repetitive peak reverse voltage		600	V	
$I_{F(RMS)}$	Repetitive peak reverse voltage		10	A	
$I_{F(AV)}$	Average forward current $\delta = 0.5$ , square wave	DO-201AD	$T_L = 80\text{ °C}$	3	A
		SMB	$T_L = 55\text{ °C}$		
		SMC	$T_L = 80\text{ °C}$		
$I_{FSM}$	Surge non repetitive forward current	DO-201AD	$t_p = 10\text{ ms}$ sinusoidal	55	A
		SMB / SMC		45	
$T_{stg}$	Storage temperature range		-65 to +175	°C	
$T_j$	Maximum operating junction temperature		+175	°C	

**Table 2. Thermal resistance parameter**

Symbol	Parameter		Max. value	Unit
$R_{th(j-l)}$	Junction to lead	SMC	20	°C/W
		SMB	25	
	Junction to lead	Lead length = 10 mm	DO-201AD	
Junction to ambient	75			

For more information, refer to the following application note :

- AN5088 : Rectifiers thermal management, handling and mounting recommendations

**Table 3. Static electrical characteristics**

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25\text{ °C}$	$V_R = V_{RRM}$	-		3	$\mu\text{A}$
		$T_j = 150\text{ °C}$		-	15	100	
$V_F^{(2)}$	Forward voltage drop	$T_j = 25\text{ °C}$	$I_F = 3\text{ A}$	-		1.7	V
		$T_j = 150\text{ °C}$		-	1.0	1.25	

1. Pulse test:  $t_p = 5\text{ ms}$ ,  $\delta < 2\%$

2. Pulse test:  $t_p = 380\text{ }\mu\text{s}$ ,  $\delta < 2\%$

To evaluate the conduction losses, use the following equation:

$$P = 1.03 \times I_{F(AV)} + 0.09 \times I_{F(RMS)}^2$$

For more information, refer to the following application notes related to the power losses :

- AN604: Calculation of conduction losses in a power rectifier
- AN4021: Calculation of reverse losses on a power diode

**Table 4. Dynamic characteristics ( $T_j = 25\text{ °C}$  unless otherwise stated)**

Symbol	Parameters	Test conditions	Min.	Typ.	Max.	Unit
$t_{rr}$	Reverse recovery time	$I_F = 0.5\text{ A}$ , $I_{rr} = 0.25\text{ A}$ , $I_R = 1\text{ A}$	-		30	ns
		$I_F = 1\text{ A}$ , $dI_F/dt = -50\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$	-	35		
$t_{fr}$	Forward recovery time	$I_F = 3\text{ A}$ , $dI_F/dt = 100\text{ A}/\mu\text{s}$ , $V_{FR} = 1.1 V_{F(max.)}$	-		100	ns
$V_{FP}$	Forward recovery voltage	$I_F = 3\text{ A}$ , $dI_F/dt = 100\text{ A}/\mu\text{s}$	-		10	V

## 1.1 Characteristics (curves)

Figure 1. Conduction losses versus average current

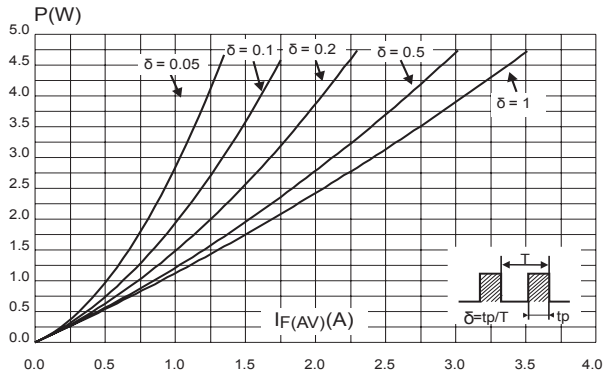


Figure 2. Forward voltage drop versus forward current

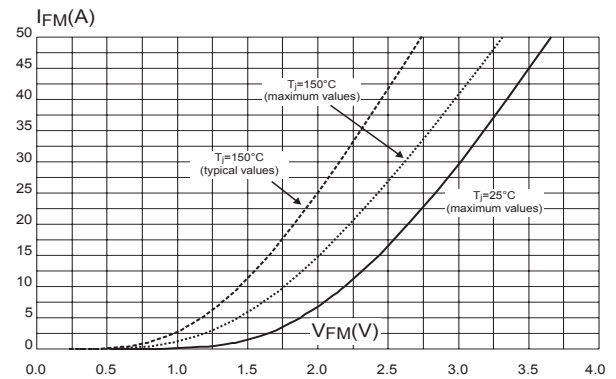


Figure 3. Relative variation of thermal impedance junction to ambient versus pulse duration (epoxy printed circuit FR4,  $L_{leads} = 10\text{ mm}$ ,  $S_{Cu} = 1\text{ cm}^2$ )

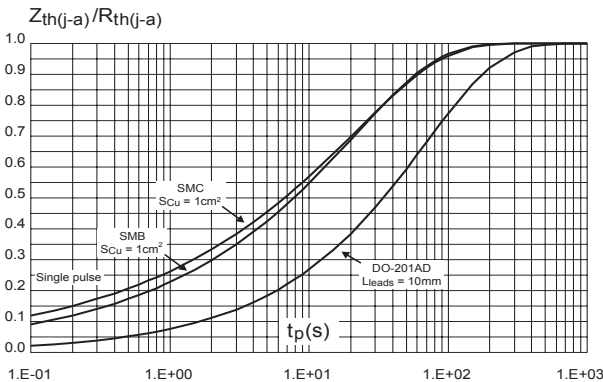


Figure 4. Peak reverse recovery current versus  $di_F/dt$  (typical values)

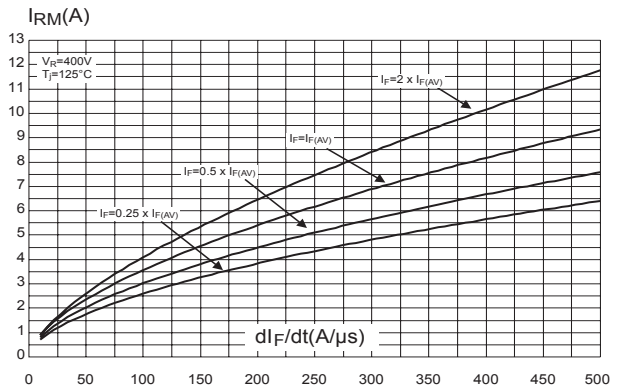


Figure 5. Reverse recovery time versus  $di_F/dt$  (typical values)

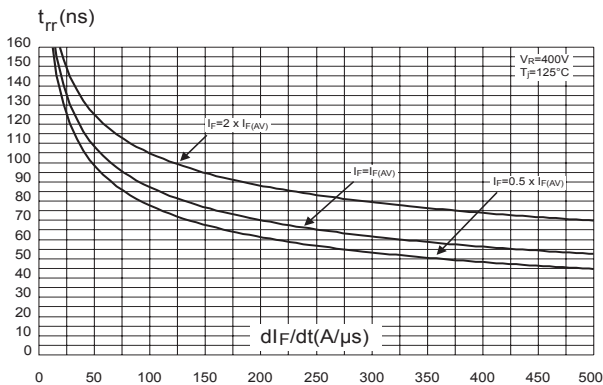


Figure 6. Reverse recovery charges versus  $di_F/dt$  (typical values)

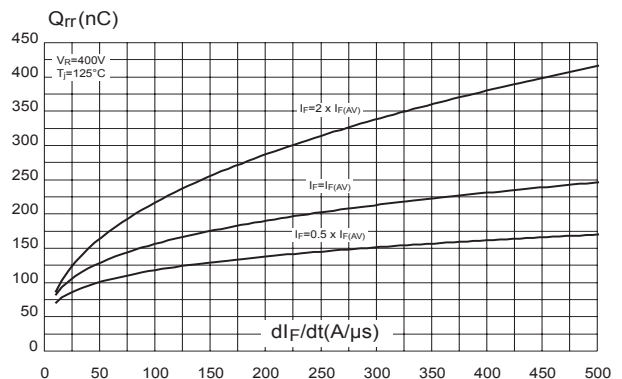


Figure 7. Softness factor versus  $di_F/dt$  (typical values)

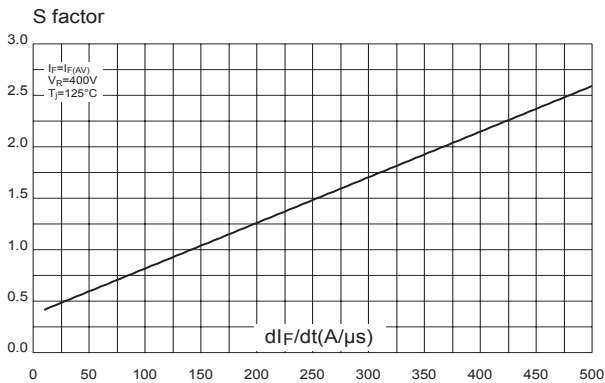


Figure 8. Relative variations of dynamic parameters versus junction temperature

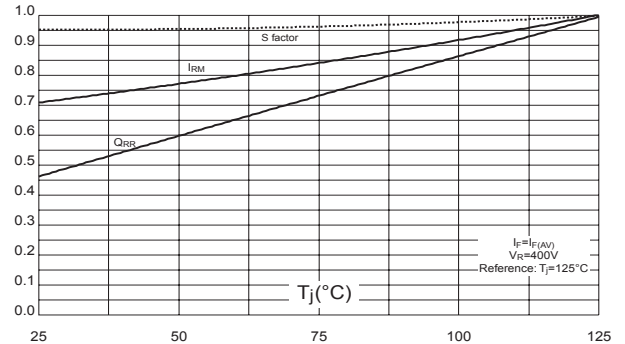


Figure 9. Transient peak forward voltage versus  $di_F/dt$  (typical values)

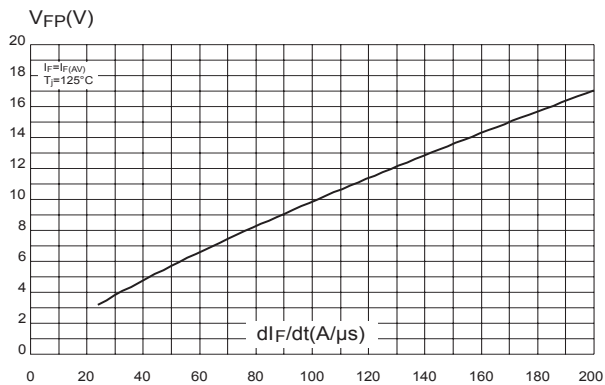


Figure 10. Forward recovery time versus  $di_F/dt$  (typical values)

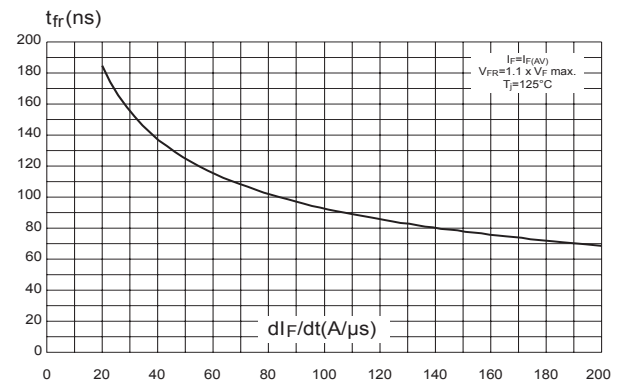


Figure 11. Junction capacitance versus reverse voltage applied (typical values)

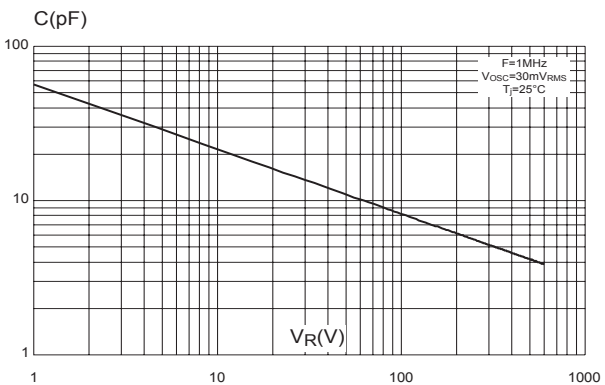
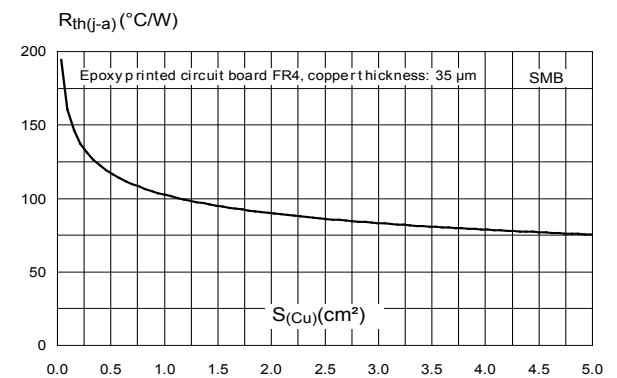
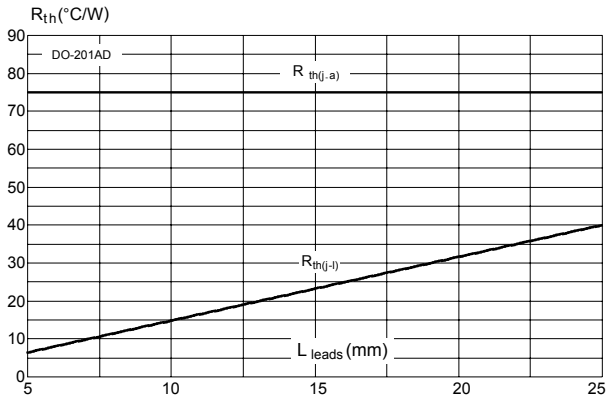


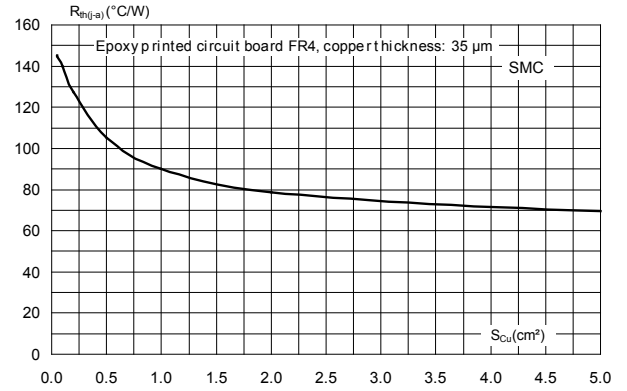
Figure 12. Thermal resistance junction to ambient versus copper surface under each lead (typical values) (SMB)



**Figure 13. Thermal resistance versus lead length (DO-201AD)**



**Figure 14. Thermal resistance junction to ambient versus copper surface under each lead (typical values) (SMC)**



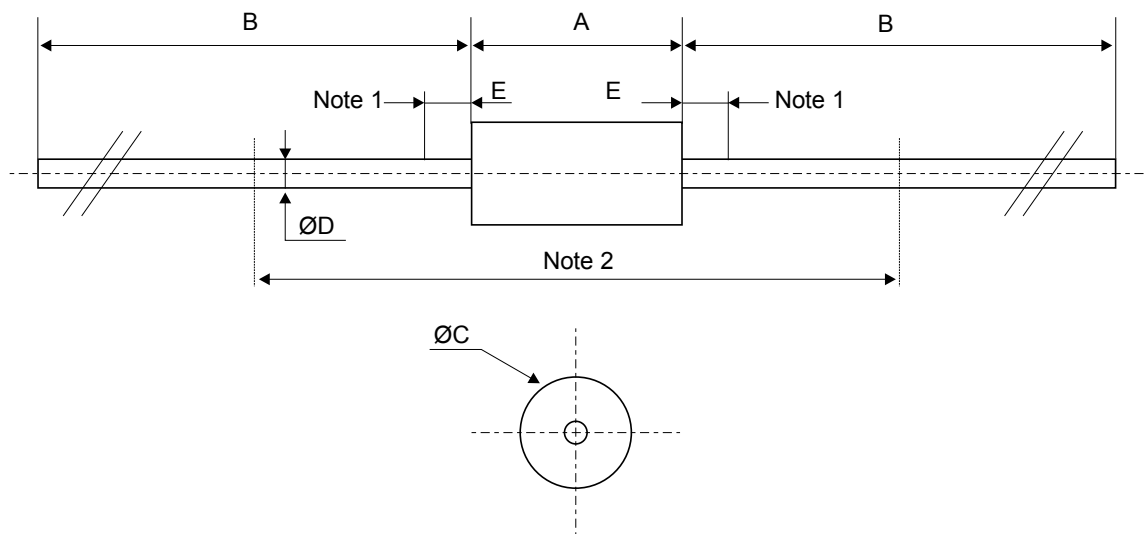
## 2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 2.1 DO-201AD package information

- Epoxy meets UL 94, V0

**Figure 15. DO-201AD package outline**



**Table 5. DO-201AD package mechanical data**

Ref.	Dimensions					
	Millimeters			Inches (for reference only)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A		-	9.50		-	0.374
B	25.40	-		1.000	-	
C		-	5.30		-	0.209
D <sup>(1)</sup>		-	1.30		-	0.051
E		-	1.25		-	0.049
Note 2 <sup>(2)</sup>	15.00			0.590		

1. The lead diameter *D* is not controlled over zone *E*
2. The minimum length, which must stay straight between the right angles after bending, is 15 mm (0.59")

## 2.2 SMB package information

- Epoxy meets UL94, V0
- Lead-free package

Figure 16. SMB package outline

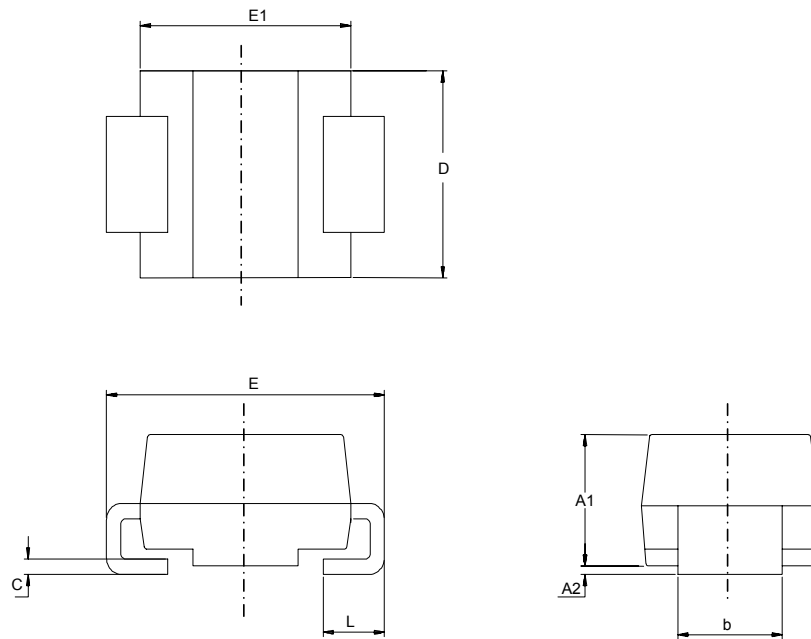
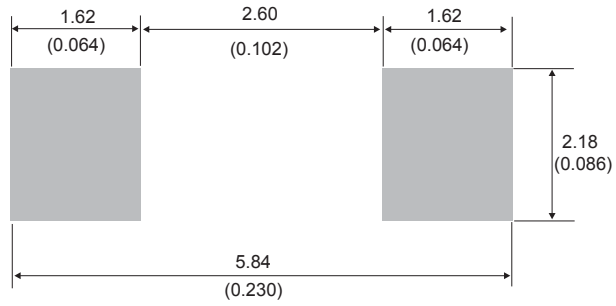


Table 6. SMB package mechanical data

Ref.	Dimensions			
	Millimeters		Inches (for reference only)	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.074	0.097
A2	0.05	0.20	0.001	0.008
b	1.95	2.20	0.076	0.087
c	0.15	0.40	0.005	0.016
D	3.30	3.95	0.129	0.156
E	5.10	5.60	0.200	0.221
E1	4.05	4.60	0.159	0.182
L	0.75	1.50	0.029	0.060



**Figure 17. SMB recommended footprint**



### 2.3 SMC package information

- Epoxy meets UL94, V0

Figure 18. SMC package outline

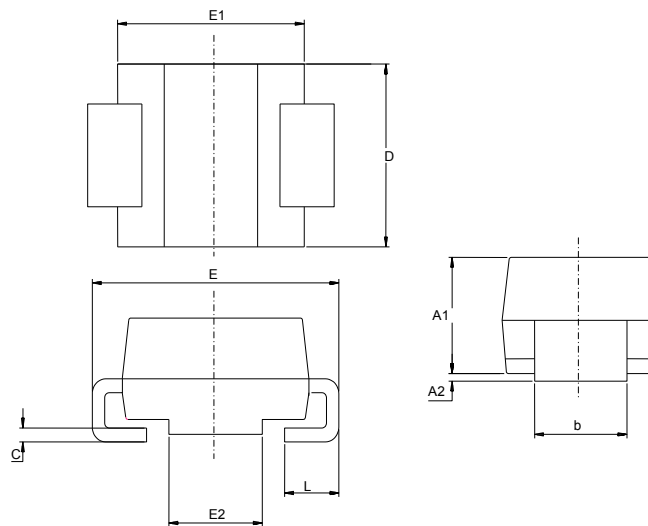
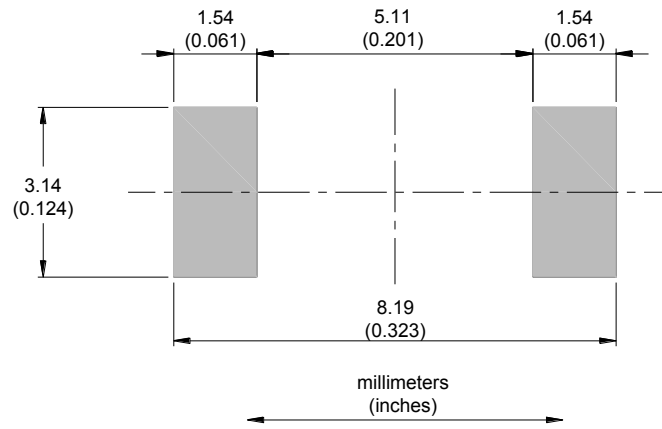


Table 7. SMC package mechanical data

Ref.	Dimensions			
	Millimeters		Inches (for reference only)	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.0748	0.0965
A2	0.05	0.20	0.0020	0.0079
b	2.90	3.20	0.1142	0.1260
c	0.15	0.40	0.0059	0.0157
D	5.55	6.25	0.2185	0.2461
E	7.75	8.15	0.3051	0.3209
E1	6.60	7.15	0.2598	0.2815
E2	4.40	4.70	0.1732	0.1850
L	0.75	1.50	0.0295	0.0591

**Figure 19. SMC recommended footprint**



### 3 Ordering information

**Table 8. Ordering information**

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STTH3R06	STTH3R06	DO-201AD	1.16 g	600	Ammopack
STTH3R06-RL	STTH3R06	DO-201AD	1.16 g	1900	Tape and reel
STTH3R06U	3R6U	SMB	0.107 g	2500	Tape and reel
STTH3R06S	R6S	SMC	0.245 g	2500	Tape and reel

## Revision history

**Table 9. Document revision history**

Date	Revision	Changes
Mar-2003	1	First issue
07-Sep-2004	2	SMB and SMC packages added
14-Oct-2005	3	Changed marking of STTH3R06U from R06U to 3R6U on page 1. Added ECOPACK statement.
21-Oct-2021	4	Updated pin names. Minor text changes.

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